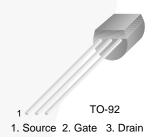


September 2016

2N7000BU / 2N7000TA **Advanced Small-Signal MOSFET**

Features

- · Fast Switching Times
- · Improved Inductive Ruggedness
- · Lower Input Capacitance
- Extended Safe Operating Area
- · Improved High-Temperature Reliability



Description

These N-channel enhancement mode field effect transistors are produced using Fairchild's proprietary, high cell density, DMOS technology. These products minimize onstate resistance while providing rugged, reliable, and fast switching performance. They can be used in most applications requiring up to 400 mA DC and can deliver pulsed currents up to 2 A. These products are particularly suited for low-voltage, low-current applications, such as small servo motor control, power MOSFET gate drivers, and other switching applications.

Ordering Information

Part Number	t Number Marking Package		Packing Method	
2N7000BU	2N7000	TO-92 3L	Bulk	
2N7000TA	2N7000	TO-92 3L	Ammo	

Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only. Values are at T_C = 25°C unless otherwise noted.

Symbol	Parameter	Value	Unit	
V _{DSS}	Drain-to-Source Voltage	60	V	
	Continuous Drain Current (T _C = 25°C)		mA	
ID	Continuous Drain Current (T _C = 100°C)	110	IIIA	
I _{DM}	Drain Current Pulsed ⁽¹⁾	1000	mA	
V _{GS}	Gate-to-Source Voltage	±30	V	
T _{J,} T _{STG}	Operating Junction and Storage Temperature Range	-55 to 150	°C	
T _L	Maximum Lead Temperature for Soldering Purposes, 1/8-inch from Case for 5 Seconds	300	°C	

1

Note:

1. Repetitive rating: pulse width limited by maximum junction temperature.

Thermal Characteristics(2)

Values are at $T_C = 25$ °C unless otherwise noted.

Symbol	Parameter	Value	Unit
В	Total Power Dissipation (T _C = 25°C)	400	mW
P _D	Linear Derating Factor	3.2	mW/°C
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	312.5	°C/W

Note:

2. Device mounted on FR-4 PCB, board size = 101.5 mm x 114.5 mm.

Electrical Characteristics

Values are at $T_C = 25$ °C unless otherwise noted.

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit	
BV _{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	60			V	
V _{GS(th)}	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	0.3		3.9	V	
	Gate Threshold Voltage	$V_{DS} = V_{GS}$, $I_D = 1 \text{ mA}$	0.4		3.0		
14	Gate-Source Leakage, Forward	V _{GS} = 15 V			100	n /	
I _{GSS}	Gate-Source Leakage, Reverse	V _{GS} = -15 V			-100	nA	
I _{DSS}	Drain-to-Source Leakage Current	V _{DS} = 60 V			1	μА	
		$V_{DS} = 45 \text{ V}, T_{C} = 125^{\circ}\text{C}$			1000		
R _{DS(ON)}	Static Drain-Source On-State Resistance ⁽³⁾	$V_{GS} = 10 \text{ V}, I_D = 0.5 \text{ A}$			5.0	Ω	
9 _{fs}	Forward Transconductance ⁽³⁾	V _{DS} = 15 V, I _D = 0.5 A	0.1	0.3		S	
C _{iss}	Input Capacitance			30		pF	
C _{oss}	Output Capacitance	$V_{GS} = 0 \text{ V}, V_{DS} = 25 \text{ V}, f = 1 \text{ MHz}$		12		pF	
C _{rss}	Reverse Transfer Capacitance			3.0		pF	
t _{d(on)}	Turn-On Delay				10	ns	
t _r	Rise Time	$V_{DD} = 30 \text{ V}, I_{D} = 0.5 \text{ A},$ $R_{G} = 15 \Omega^{(3),(4)}$			10	ns	
t _{d(off)}	Turn-Off Delay	$R_G = 15 \Omega^{(3),(4)}$	/		10	ns	
t _f	Fall Time				10	ns	

Notes:

- 3. Pulse test: pulse width = 250 μ s, duty cycle \leq 2%.
- 4. Essentially independent of operating temperature.

Physical Dimensions TO-92 15.62 13.20 0.56 NOTES: UNLESS OTHERWISE SPECIFIED DRAWING WITH REFERENCE TO JEDEC TO-92 RECOMMENDATIONS. ALL DIMENSIONS ARE IN MILLIMETERS. DRAWING CONFORMS TO ASME Y14.5M-2009. DRAWING FILENAME: MKT-ZAO3DREV4. 2 3

Figure 1. 3-LEAD, TO-92, JEDEC TO-92 COMPLIANT STRAIGHT LEAD CONFIGURATION

Package drawings are provided as a service to customers considering Fairchild components. Drawings may change in any manner without notice. Please note the revision and/or date on the drawing and contact a Fairchild Semiconductor representative to verify or obtain the most recent revision. Package specifications do not expand the terms of Fairchild's worldwide terms and conditions, specifically the warranty therein, which covers Fairchild products.

Always visit Fairchild Semiconductor's online packaging area for the most recent package drawings: http://www.fairchildsemi.com/dwg/ZA/ZA03D.pdf.

For current tape and reel specifications, visit Fairchild Semiconductor's online packaging area: http://www.fairchildsemi.com/packing_dwg/PKG-ZA03D_BK.pdf.

Physical Dimensions (Continued)

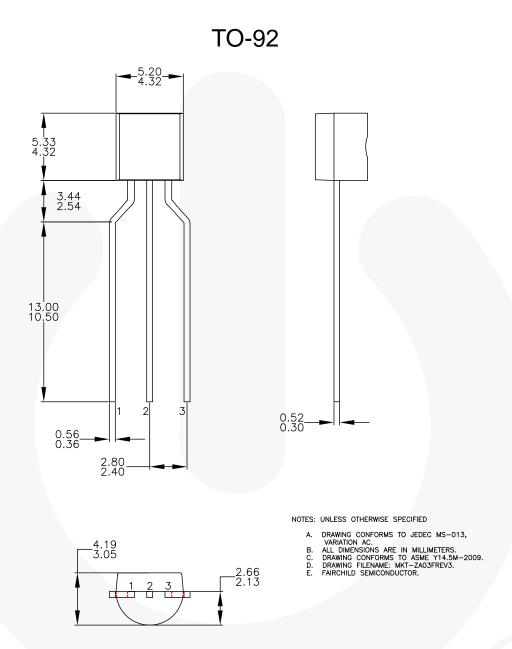


Figure 2. 3-LEAD, TO-92, MOLDED 0.200 IN LINE SPACING LD FORM (J61Z OPTION) (ACTIVE)

Package drawings are provided as a service to customers considering Fairchild components. Drawings may change in any manner without notice. Please note the revision and/or date on the drawing and contact a Fairchild Semiconductor representative to verify or obtain the most recent revision. Package specifications do not expand the terms of Fairchild's worldwide terms and conditions, specifically the warranty therein, which covers Fairchild products.

Always visit Fairchild Semiconductor's online packaging area for the most recent package drawings: http://www.fairchildsemi.com/dwg/ZA/ZA03F.pdf.

For current tape and reel specifications, visit Fairchild Semiconductor's online packaging area: http://www.fairchildsemi.com/packing_dwg/PKG-ZA03F.pdf.





TRADEMARKS

The following includes registered and unregistered trademarks and service marks, owned by Fairchild Semiconductor and/or its global subsidiaries, and is not intended to be an exhaustive list of all such trademarks.

AccuPower™ F-PFS™ AttitudeEngine™ **FRFET®**

Global Power Resource SM Awinda[®]

AX-CAP®* GreenBridge™ RitSiC™ Green FPS™ Build it Now™ Green FPS™ e-Series™

CorePLUS™ Gmax™ CorePOWER™ GTO™ CROSSVOLT™ IntelliMAX™ **CTL™**

ISOPLANAR™ Current Transfer Logic™ Making Small Speakers Sound Louder

DEUXPEED® and Better™ Dual Cool™ MegaBuck™ EcoSPARK® MIČROCOUPLER™ EfficientMax™ MicroFET™ **ESBC™**

MicroPak™ MicroPak2™ MillerDrive™ MotionMax™

Fairchild Semiconductor® MotionGrid® FACT Quiet Series™ MTi[®] $\text{MTx}^{\tiny{\circledR}}$ MVN® mWSaver® OptoHiT™ OPTOLOGIC® OPTOPLANAR®

Power Supply WebDesigner™ PowerTrench®

PowerXS^{TI}

Programmable Active Droop™

QS™ Quiet Series™ RapidConfigure™

OFFT

Saving our world, 1mW/W/kW at a time™

SignalWise™ SmartMax™ SMART START™

Solutions for Your Success™

SPM® STEALTH™ SuperFET® SuperSOT™-3 SuperSOT™-6 SuperSOT™-8 SupreMOS® SyncFET™ Sync-Lock™

SYSTEM SYSTEM TinyBoost[®]

TinyBuck[®] TinyCalc™ TinyLogic[®] TINYOPTO™ TinvPower™ TinyPWM™ TinyWire™ TranSiC™

TriFault Detect™ TRUECURRENT®* սSerDes™

UHC Ultra FRFET™ UniFET™ VCX™ VisualMax™

VoltagePlus™ XS™ Xsens™ 仙童®

■®

Fairchild®

FastvCore™

FETBench™

FACT[®]

FPS™

FAIRCHILD SEMICONDUCTOR RESERVES THE RIGHT TO MAKE CHANGES WITHOUT FURTHER NOTICE TO ANY PRODUCTS HEREIN TO IMPROVE RELIABILITY, FUNCTION, OR DESIGN. TO OBTAIN THE LATEST, MOST UP-TO-DATE DATASHEET AND PRODUCT INFORMATION, VISIT OUR AIRCHILDSEMI.COM, FAIRCHILD DOES NOT ASSUME ANY LIABILITY ARISING OUT OF THE APPLICATION OR USE OF ANY PRODUCT OR CIRCUIT DESCRIBED HEREIN; NEITHER DOES IT CONVEY ANY LICENSE UNDER ITS PATENT RIGHTS, NOR THE RIGHTS OF OTHERS. THESE SPECIFICATIONS DO NOT EXPAND THE TERMS OF FAIRCHILD'S WORLDWIDE TERMS AND CONDITIONS, SPECIFICALLY THE WARRANTY THEREIN, WHICH COVERS THESE PRODUCTS.

Unless otherwise specified in this data sheet, this product is a standard commercial product and is not intended for use in applications that require extraordinary levels of quality and reliability. This product may not be used in the following applications, unless specifically approved in writing by a Fairchild officer: (1) automotive or other transportation, (2) military/aerospace, (3) any safety critical application - including life critical medical equipment - where the failure of the Fairchild product reasonably would be expected to result in personal injury, death or property damage. Customer's use of this product is subject to agreement of this Authorized Use policy. In the event of an unauthorized use of Fairchild's product, Fairchild accepts no liability in the event of product failure. In other respects, this product shall be subject to Fairchild's Worldwide Terms and Conditions of Sale, unless a separate agreement has been signed by both Parties.

ANTI-COUNTERFEITING POLICY

Fairchild Semiconductor Corporation's Anti-Counterfeiting Policy. Fairchild's Anti-Counterfeiting Policy is also stated on our external website, www.fairchildsemi.com,

Counterfeiting of semiconductor parts is a growing problem in the industry. All manufacturers of semiconductor products are experiencing counterfeiting of their parts. Customers who inadvertently purchase counterfeit parts experience many problems such as loss of brand reputation, substandard performance, failed applications, and increased cost of production and manufacturing delays. Fairchild is taking strong measures to protect ourselves and our customers from the proliferation of counterfeit parts. Fairchild strongly encourages customers to purchase Fairchild parts either directly from Fairchild or from Authorized Fairchild Distributors who are listed by country on our web page cited above. Products customers buy either from Fairchild directly or from Authorized Fairchild Distributors are genuine parts, have full traceability, meet Fairchild's quality standards for handling and storage and provide access to Fairchild's full range of up-to-date technical and product information. Fairchild and our Authorized Distributors will stand behind all warranties and will appropriately address any warranty issues that may arise. Fairchild will not provide any warranty coverage or other assistance for parts bought from Unauthorized Sources. Fairchild is committed to combat this global problem and encourage our customers to do their part in stopping this practice by buying direct or from authorized distributors.

PRODUCT STATUS DEFINITIONS

Definition of Terms

Definition of Terms			
Datasheet Identification	Product Status	Definition	
Advance Information	Formative / In Design	Datasheet contains the design specifications for product development. Specifications may change in any manner without notice.	
Preliminary	First Production	Datasheet contains preliminary data; supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.	
No Identification Needed	Full Production	Datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve the design.	
Obsolete	Not In Production	Datasheet contains specifications on a product that is discontinued by Fairchild Semiconductor. The datasheet is for reference information only.	

Rev 177

^{*} Trademarks of System General Corporation, used under license by Fairchild Semiconductor.